



Media Release

UTAC delivers high-density System in a Package (SiP) Service for Octavo Systems

Singapore, 26 February, 2018 – UTAC Holdings Ltd ("UTAC"), a global semiconductor test and assembly services provider, through ongoing investments in its Dongguan facility, is now enabled with capabilities to serve the most demanding System in a Package (SiP) applications, where high integrated component density is required for advanced functionality and performance.

Octavo Systems OSD335x-SM is a leading example of a demanding SiP application. Octavo's OSD335x-SM SiP product, integrates a Texas Instruments ARM Cortex®-A8 processor to deliver the smallest embedded computing solution in the market. It is 60% smaller than a PCB assembly implementation of discrete components. This high-density SiP product integrates 4 bare die and 94 SMT devices in a 21x21mm ball grid array (BGA).

Mr. Bill Heye, President of Octavo Systems said: "Octavo's new System in Package enables embedded systems design engineers to take advantage of its miniaturization while also accelerating their design cycle. Our customer's supply chain management also appreciate the simplified sourcing of one SiP instead of 150 separate components."

UTAC's Dongguan, China facility, also known as UDG was acquired by UTAC in 2010 and has been a global supplier of assembly and test services for a variety of products in the communications, industrial and consumer products segments.

Dr. John Nelson, Chief Executive Officer, UTAC said: "We are committed to building a strong partnership with Octavo and play an instrumental role in supporting the company in delivering fully integrated SiP based products. This project signifies UTAC's key growth priorities, which include investing and developing SiP with key partners."

"Octavo was able to work closely with UTAC engineers and production staff on design, production ramp, and quality processes. We have appreciated UTAC's ability to quickly bring expertise from across the company to successfully bring this complex SiP into production," added Mr. Bill Heye.

Mr. HC Tan, General Manager, UTAC Greater China Operations, said: "Our collaboration first began at the substrate design phase where we teamed up with Octavo to meet challenging performance requirements for a six-layer high-density substrate. Next, we worked jointly to qualify the substrate and our SiP assembly process. UDG's fully integrated SMT line capability was critical in cost effectively placing 94 SMT components in close proximity. The team successfully addressed the challenge of encapsulating a large DRAM BGA package with tight clearances. UDG has successfully since ramped into volume production."

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About UTAC Holdings Ltd

UTAC Holdings Ltd (UTAC) is a leading independent provider of assembly and test services for a broad range of semiconductor chips. We offer a full range of semiconductor assembly and test services in these key product categories: analog, mixed-signal and logic, and memory. Our customers are primarily fabless companies, integrated device manufacturers and wafer foundries. UTAC is headquartered in Singapore, with production facilities located in Singapore, Thailand, Taiwan, China, Indonesia, and Malaysia. We have a global sales network across United States, Japan, China and Taiwan, rest of Asia and Europe, with sales offices in each of these regions.

About Octavo Systems

Octavo Systems was founded in 2013 by four senior semiconductor technology leaders, all of whom had been associated with Texas Instruments. They founded Octavo on the observation that Moore's law applies to the size of semiconductor components rather than to systems. As semiconductor designers continue to push the boundaries of size, power, and performance it is becoming exorbitantly expensive to integrate all of the system functions into a single semiconductor substrate. Major semiconductor manufacturers have been aware of this for some time and have instead packaged multiple die with different functions into a single package to meet their requirements. Unfortunately, this ability has only been accessible to the largest customers or to very specific products in high-priced applications.

Octavo Systems' mission is to bring these capabilities to the masses, allowing the idea behind Moore's law to continue at the system level. Through our technology and design innovations we are making this technology *more accessible* to all, allowing for the continued development of *smaller, cheaper*, and **more innovative** products.